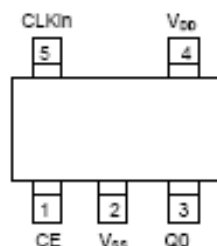
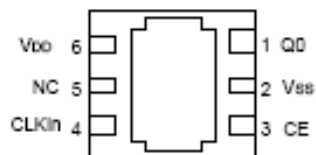


PIN CONFIGURATION



SOT-25
(TOP VIEW)

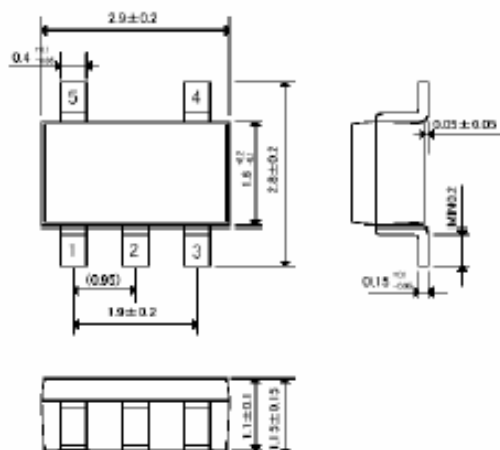


USP-6C
(BOTTOM VIEW)

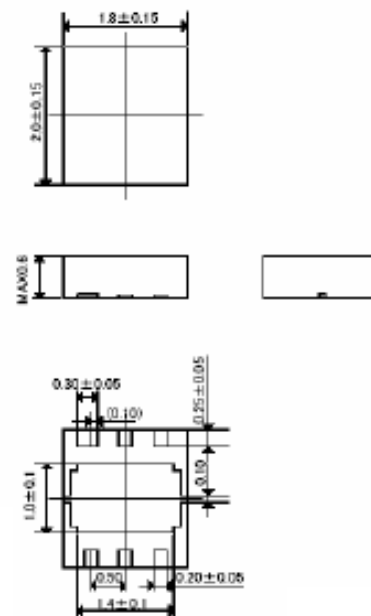
* The dissipation pad (TAB) of the bottom view of the USP-6C package should be connected to the V_{SS} (No. 2) pin.

PACKAGE INFORMATION

SOT-25



USP-6C



* No. 1 pin is larger than the other pins.
Soldering fillet surface is not formed because the sides of the pins are not plated.